# **Trench Power MOSFET**

# 12 V, 3.3 A, Single P-Channel, ESD Protected SC-88

#### **Features**

- Leading Trench Technology for Low R<sub>DS(ON)</sub> Extending Battery Life
- SC-88 Small Outline (2x2 mm, SC70-6 Equivalent)
- Gate Diodes for ESD Protection
- Pb-Free Package is Available

#### **Applications**

- High Side Load Switch
- Cell Phones, Computing, Digital Cameras, MP3s and PDAs

### **MAXIMUM RATINGS** ( $T_J = 25$ °C unless otherwise stated)

Param	Symbol	Value	Units			
Drain-to-Source Voltage			$V_{DSS}$	-12	V	
Gate-to-Source Voltage			$V_{GS}$	±12	V	
Continuous Drain Current (Note 1)	Steady	T <sub>A</sub> = 25 °C	I <sub>D</sub>	-2.7	Α	
	State	T <sub>A</sub> = 85 °C		-2.0		
	t≤5 s	T <sub>A</sub> = 25 °C		-3.3		
Power Dissipation (Note 1)	Steady State	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.625	W	
Pulsed Drain Current $t_p = 10 \mu s$			I <sub>DM</sub>	-8.0	Α	
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C	
Source Current (Body Diode)			I <sub>S</sub>	-0.8	Α	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T <sub>L</sub>	260	°C	

#### THERMAL RESISTANCE RATINGS (Note 1)

Parameter	Symbol	Max	Units
Junction-to-Ambient - Steady State	$R_{\theta JA}$	200	°C/W
Junction-to-Ambient - t ≤ 5 s	$R_{\theta JA}$	141	
Junction-to-Lead - Steady State	$R_{\theta JL}$	102	

Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).



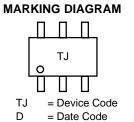
#### ON Semiconductor®

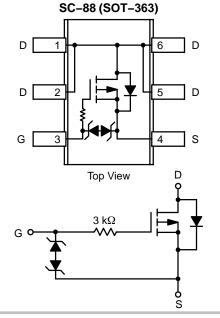
#### http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> Max
	45 m $\Omega$ @ $-4.5$ V	
–12 V	67 mΩ @ -2.5 V	-3.3 A
	133 mΩ @ –1.8 V	



SC-88 (SOT 363) CASE 419B STYLE 28





#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTJS3151PT1	SC-88	3000 Units/Reel
NTJS3151PT1G	SC-88 (Pb-Free)	3000 Units/Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** ( $T_J$ =25°C unless otherwise stated)

Parameter	Symbol	Test Cond	dition	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•	•	•		•		•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-12			٧
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>				10		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = -9.6 \text{ V},$ $V_{DS} = 0 \text{ V}$	T <sub>J</sub> = 25°C			-1.0	μΑ
		V <sub>DS</sub> = 0 V	T <sub>J</sub> = 125°C		-2.5		
Gate-to-Source Leakage Current	$I_{GSS}$ $V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$				±1.5	μΑ	
		$V_{DS} = 0 \text{ V}, V_{G}$	<sub>S</sub> = ±12 V			±10	mA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D}$	= 100 μΑ	-0.40			V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				3.4		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS} = -4.5 \text{ V}, I_D = -3.3 \text{ A}$			45	60	mΩ
		$V_{GS} = -2.5 \text{ V}, \text{ I}$	$V_{GS} = -2.5 \text{ V}, I_D = -2.9 \text{ A}$		67	90	
		$V_{GS} = -1.8 \text{ V},$	$V_{GS} = -1.8 \text{ V}, I_D = -1.0 \text{ A}$		133	160	
Forward Transconductance	9FS	$V_{GS} = -10 \text{ V}, I_D = -3.3 \text{ A}$			15		S
CHARGES AND CAPACITANCES							
Input Capacitance	C <sub>ISS</sub>	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = -12 \text{ V}$			850		pF
Output Capacitance	C <sub>OSS</sub>				170		
Reverse Transfer Capacitance	C <sub>RSS</sub>		-		110		
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = -4.5 \text{ V}, V_{I}$ $I_{D} = -3.$	$_{0S} = -5.0 \text{ V},$		8.6		nC
Gate-to-Source Charge	$Q_{GS}$	$I_D = -3.3 \text{ A}$			1.3		
Gate-to-Drain Charge	$Q_{GD}$				2.2		
Gate Resistance	$R_{G}$				3000		Ω
SWITCHING CHARACTERISTICS (No	ote 3)						
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS} = -4.5 \text{ V}, V_{DD} = -6.0 \text{ V},$ $I_{D} = -1.0 \text{ A}, R_{G} = 6.0 \Omega$			0.86		μs
Rise Time	t <sub>r</sub>				1.5		1
Turn-Off Delay Time	t <sub>d(OFF)</sub>				3.5		1
Fall Time	t <sub>f</sub>				3.9		
DRAIN-SOURCE DIODE CHARACTE	RISTICS (Note	2)					
Forward Diode Voltage	V <sub>SD</sub>	$V_{GS} = 0 V$	T <sub>J</sub> = 25°C		-0.85	-1.2	V
		$I_{S} = -3.3 \text{ A}$	T <sub>J</sub> = 125°C		-0.7		1

Pulse Test: pulse width ≤ 300μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

#### TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)

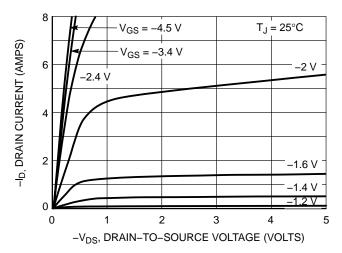
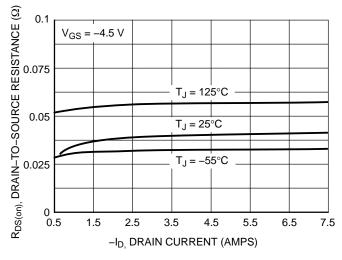


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



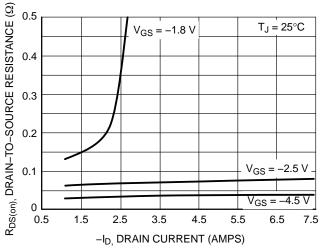


Figure 3. On–Resistance vs. Drain Current and Temperature

Figure 4. On–Resistance vs. Drain Current and Gate Voltage

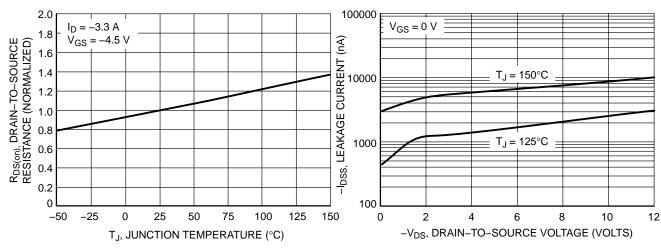
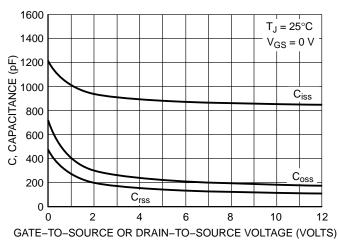


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

#### TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)



-V<sub>GS,</sub> GATE-TO-SOURCE VOLTAGE (VOLTS) 4.5 QT 3.5 3 2.5 Q2 2 Q1 1.5  $I_D = -3.3 \text{ A}$ 0.5  $T_{.J} = 25^{\circ}C$ 0 2 6 4 8 10 0 Q<sub>g</sub>, TOTAL GATE CHARGE (nC)

Figure 7. Capacitance Variation

Figure 8. Gate-to-Source Voltage vs. Total Gate Charge

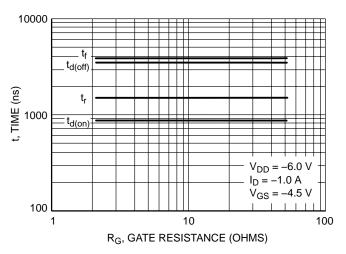


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

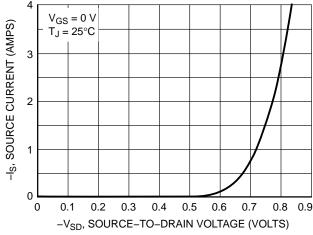
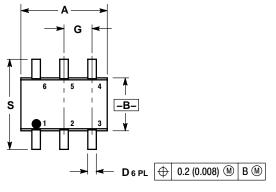
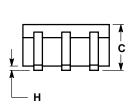


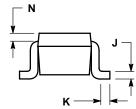
Figure 10. Diode Forward Voltage vs. Current

#### **PACKAGE DIMENSIONS**

SC-88 (SOT-363) CASE 419B-02 ISSUE U





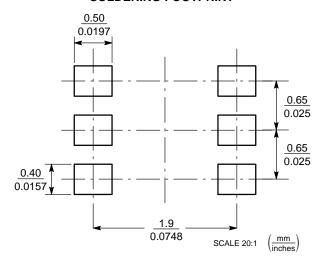


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	INC	HES	MILLIM	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026 BSC		0.65 BSC		
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008 REF		0.20 REF		
S	0.079	0.087	2.00	2 20	

STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN

#### **SOLDERING FOOTPRINT\***



#### SC-88/SC70-6/SOT-363

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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